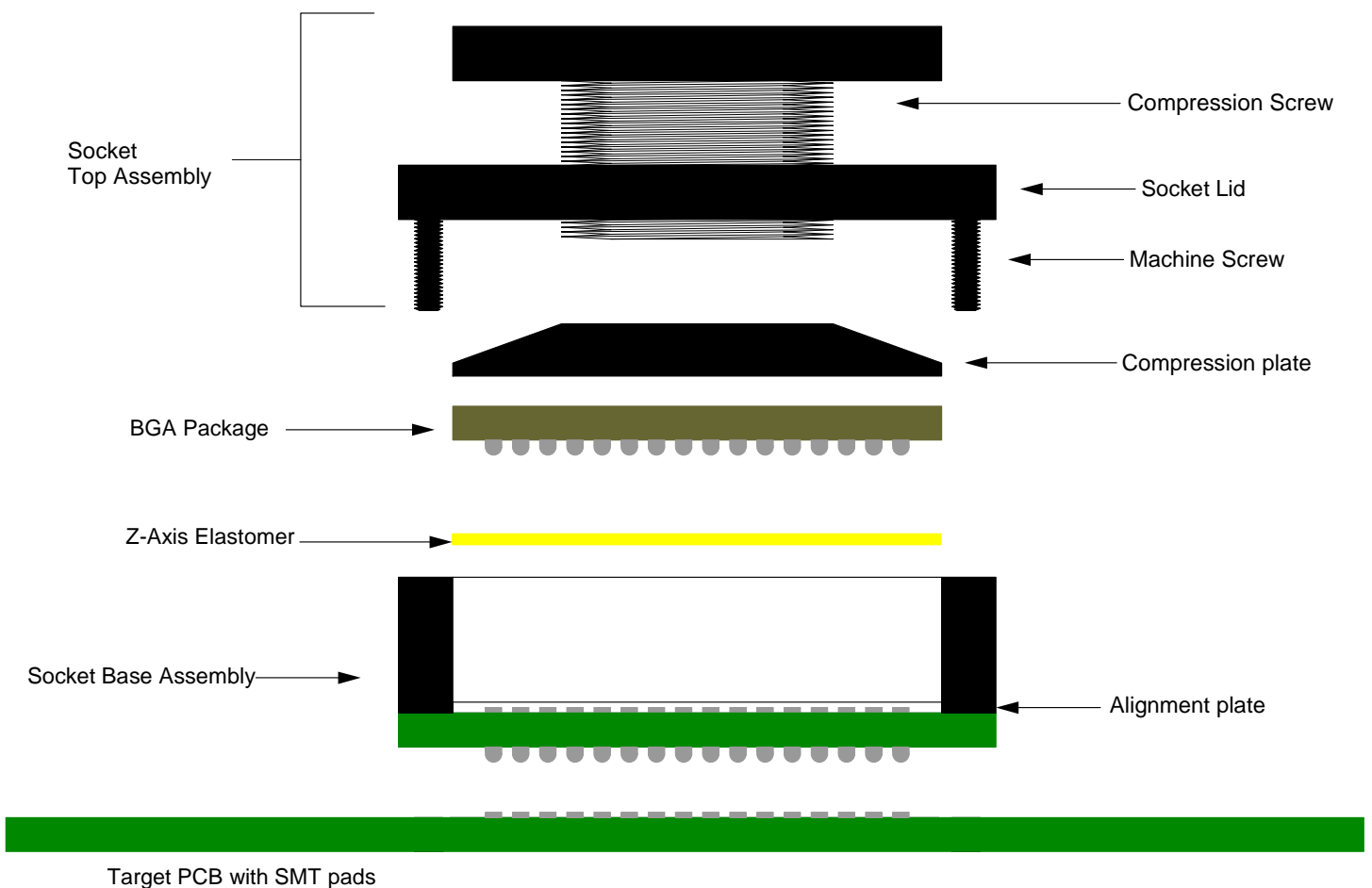


# GHz BGA Socket (surface mount) Assembly Instructions

1. Reflow Socket Base assembly to the target PCB (see page 2 for reflow profile).
2. Place the square piece of elastomer provided into the socket base (rotation and 'side up' orientation are not critical).
3. Adjust the elastomer to sit into the alignment plate cavity.
4. Place BGA package (solder ball side down) into the socket. NOTE: BGA orientation on target PCB is critical.
5. Place the compression plate (if required\*) on top of the BGA package.
6. Install the socket top assembly with the hardware provided (four 0-80 screws).
7. Turn the compression screw clockwise, until it makes contact with the compression plate or the BGA package.
8. Turn an additional quarter-turn.

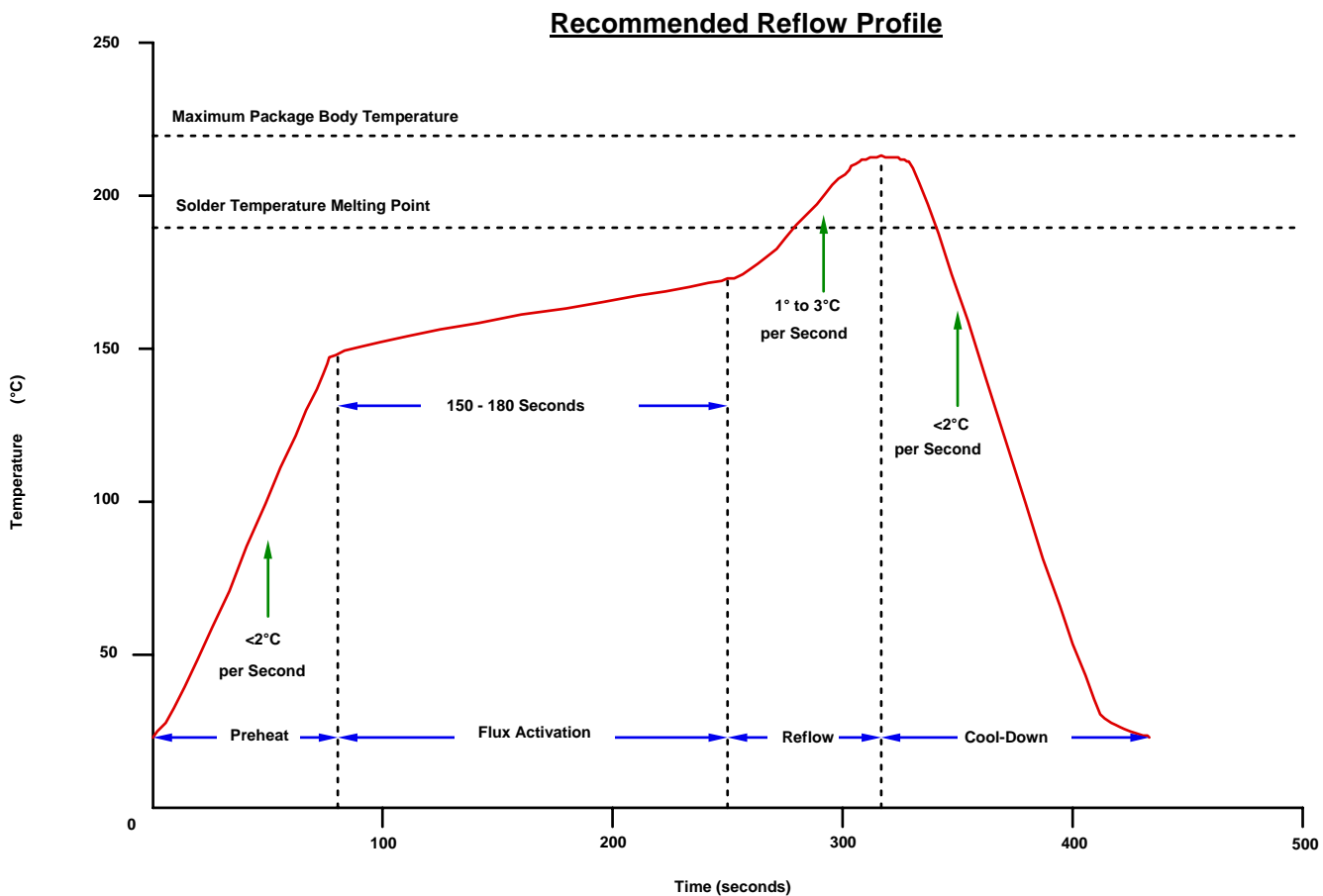


\*Ironwood Electronics technical staff will determine (from your package spec) if a compression or alignment plate is required



# GHz BGA Socket (surface mount) Assembly Instructions

1. Use caution when profiling to insure minimal temperature difference (<15 C and preferably <10 C) between components
2. Forced convection reflow with nitrogen preferred (optional)
3. Preheat stage temperature ramp rate: <2 C per second
4. Time required in Flux Activation stage: 150 to 180 seconds
5. Flux Activation stage temperature range: 150 to 183 C
6. Time required in Solder stage: 60 seconds
7. Maximum temperature 210 - 220 C (Do not exceed 10 seconds at maximum temperature)
8. Cool-Down stage temperature reduction rate: <2 C per second



**NOTE:**

It may be necessary to adjust the amount of heat when attaching the part, due to the fact that the adapter mass is different from the actual IC package. Solder sphere spec = 63Sn, 37Pb and its melting point = 183 C

